



PK750 (v1.0) July 24, 2015

# 100% Material Declaration Data Sheet Spartan®-6 Cu Wire FTG256 Package

**Average Weight: 0.7530 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					<b>0.007758</b>	<b>1.030%</b>
	Silicon	7440-21-3	100.00	Main material	0.007758	
Die Attach Material					<b>0.002083</b>	<b>0.277%</b>
	Silver	7440-22-4	77.50	Main material	0.001614	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.000312	
	Acrylate monomer	Trade Secret	7.50	Main material	0.000156	
Copper Wire					<b>0.001935</b>	<b>0.257%</b>
	Cu	7440-50-8	98.25	Main material	0.001901	
	Pd	7440-05-3	1.75	Dopant	0.000034	
Mold Compound					<b>0.396260</b>	<b>52.624%</b>
	Epoxy Resin	Trade secret	7.50	Main material	0.029720	
	Phenol Resin A	9003-35-4	3.00	Main material	0.011888	
	Phenol Resin B	Trade secret	3.00	Main material	0.011888	
	Silica (Amorphous) A	60676-86-0	67.95	Filler	0.269259	
	Silica (Amorphous) B	7631-86-9	15.00	Filler	0.059439	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.011888	
	Carbon black	1333-86-4	0.55	Color agent	0.002179	
Solder Balls					<b>0.123758</b>	<b>16.435%</b>
	Tin (Sn)	7440-31-5	96.50	Main material	0.119426	
	Silver (Ag)	7440-22-4	3.00	Main material	0.003713	
	Copper (Cu)	7440-50-8	0.50	Main material	0.000619	

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Substrate					<b>0.221206</b>	<b>29.377%</b>
	Au	7440-57-5	1.818	Main material	0.004022	
	Ni	7440-02-0	12.898	Main material	0.028530	
	Cu foil	7440-50-8	28.438	Main material	0.062906	
	Cu plating	7440-50-8	17.507	Plating	0.038727	
	Continuous Filament Fiber Glass	65997-17-3	12.505	Glass Fiber	0.027662	
	BT Core	26875-67-2 21645-51-2	20.008	Core	0.044260	
	Solder Mask	147-14-8 7727-43-7 14807-96-6 7631-86-9 112-15-2 34590-94-8 103429-90-9 64742-94-5 25551-13-7 trade secret	6.826	Solder mask	0.015099	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
7/24/15	1.0	Initial Xilinx release

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